

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the specification as follows:

Replace the paragraph beginning on page 1, line 27, and ending on page 1, line 32, with the following paragraph:

-- Referring to Fig. 9, a plasma processing apparatus 2 includes a process chamber 4 which can be evacuated, a mount base 6 on which a semiconductor wafer W is mounted, and an insulating plate 8 provided in an airtight manner on a ceiling opposite to mount base 6. Insulating plate [[6]] 8 transmitting microwave is formed of aluminum nitride or the like in the shape of a disk, for example. --

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